

RJ45C5 R1U 2.8N4G/Y RL

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com



The product range encompasses the following designs:

- 90°, lying (horizontal) and 180°, standing (vertical)
- latch up / latch down
- THT, THR or SMD soldering processes
- Wide range of different design types, also with integrated LEDs and shield contact tabs
- Performance category Cat. 3 to Cat. 6
- Packed either in a tray (TY) or on a roll (tape-on-reel, RL)
- Compatible with modular RJ45 connector according to ANSI / TIA-1096-A and IEC 60603
- Dielectric strength ≥ 1500 V AC RMS (2250 V AC peak value) according to IEEE 802.3
- Dielectric strength ≥ 1500 V AC (peak value) or ≥ 1500 V DC according to IEC 60603

Properties and advantages:

- Extended temperature range of -40°C to $+85^{\circ}\text{C}$ for maximum performance
- Reinforced gold layer ($30\mu\text{m}$) for improved corrosion protection
- At least 0.3mm stand-off ensures a perfect soldering result

General ordering data

Version	PCB plug-in connector, RJ45 jacks, Cat. 5 , THT/THR solder connection, 90°, Latch option: top, Shield tabs: none, 30...80 μm Ni / $\geq 30 \mu\text{m}$ Au , LED: Yes, green, yellow, Number of poles: 12, Tape
Order No.	2562950000
Type	RJ45C5 R1U 2.8N4G/Y RL
GTIN (EAN)	4050118571974
Qty.	200 pc(s).
Packaging	Tape

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Technical data

Dimensions and weights

Depth	15.7 mm	Depth (inches)	0.618 inch
Height	16.74 mm	Height (inches)	0.659 inch
Height of lowest version	13.44 mm	Net weight	9.31 g
Width	16.4 mm	Width (inches)	0.646 inch

System specifications

Category	Cat. 5
Colour of left LED	green
Colour of right LED	yellow
LED	Yes
Latch option	top
Mounting onto the PCB	THT/THR solder connection
Number of poles	12
Number of solder pins per pole	1
Outgoing elbow	90°
Performance-Category	Cat. 5
Pitch in inches (P)	0.05 inch
Pitch in mm (P)	1.27 mm
Product family	OMNIMATE Data - RJ45 modular jack
Protection degree	IP20
Shield surface	nickel-plated
Shield tabs	none
Shielding	Yes
Shielding material	Brass
Solder eyelet hole diameter (D)	0.9 mm
Solder eyelet hole diameter tolerance (D)	± 0.1 mm
Solder pin length (l)	2.75 mm
Solder pin length tolerance	+0.2 / -0.2 mm
Solder pin length tolerance	Lower tolerance with prefix (reveals minimum) -0.2
	Upper tolerance with prefix (reveals maximum) +0.2
	Tolerance, unit mm
Soldering process	Reflow soldering, Manual soldering, Wave soldering
Type of connection	Socket connector
Wiring	8-core

Electrical properties

Dielectric strength, contact / contact	1000 V DC, 1000 V AC	Rated current	1.5 A
Rated voltage	125 V		

Standards

Connector standard	IEC 60603-7-51
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Material data

Insulating material	PA 9T	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	II
Comparative Tracking Index (CTI)	≥ 500	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact base material	Phosphor bronze alloy
Contact surface	Gold over nickel	Layer structure of plug contact	30...80 µ" Ni / ≥ 30 µ" Au
Storage temperature, min.	-40 °C	Storage temperature, max.	85 °C
Operating temperature, min.	-40 °C	Operating temperature, max.	85 °C

Creation date March 29, 2021 7:36:02 PM CEST

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Packing

Packaging	Tape	VPE length	0 m
VPE width	0 m	VPE height	0 m
Tape reel diameter $\varnothing$ (A)	330 mm	Surface resistance	$R_s = 10^9 - 10^{12} \Omega$

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01

Approvals

Approvals



ROHS	Conform
UL File Number Search	E471884

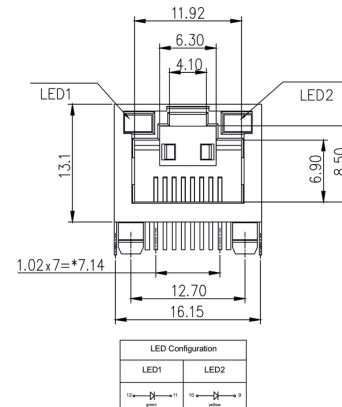
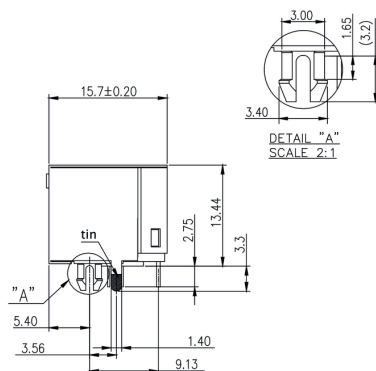
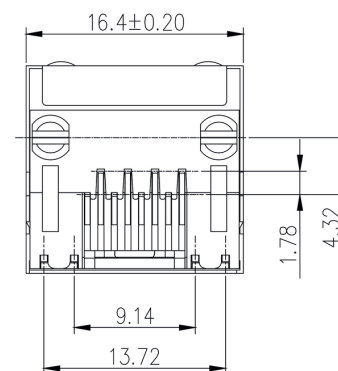
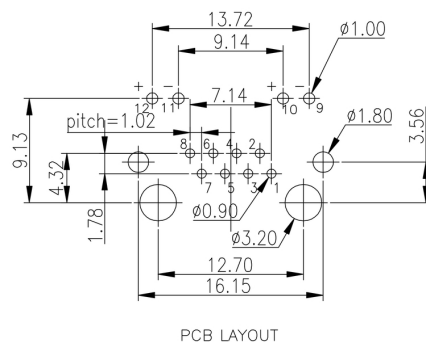
Downloads

Engineering Data [STEP](#)

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Drawings
Dimensioned drawing

Dimensioned drawing

Dimensioned drawing

PCB design


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Drawings

RJ45	G1	R	1	U	3.2	E	4	GY/GY	TY	RJ45G1 R1U 3.2E4GY/GY TY
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Recommended wave soldering profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.